

*Subj* --29. (Amended) An ink jet printing module comprising a piezoelectric element having a surface, and a thermoplastic bonding component, the thermoplastic bonding component having dimensions of a surface of a first component heat-bonded to the surface.--

D3

D4

*Subj* --46. (Amended) A method of manufacturing an ink jet printing module comprising:  
contacting a first component of an ink jet printing module having a surface with a thermoplastic bonding component;  
contacting a second component of the ink jet printing module including a orifice plate having a surface with the thermoplastic bonding component; and  
adhering a peelable protector strip over the orifice plate.--

Please add new claims 47 to 65.

*filter 1.50* 47. --<sup>50</sup><sub>47</sub>. (New) The method of claim 1 wherein the thermoplastic bonding component includes a plurality of openings.--

*Subj E1* 48. --<sup>51</sup><sub>48</sub>. (New) The method of claim 21 wherein the thermoplastic bonding component includes a plurality of openings.--

49. --<sup>52</sup><sub>49</sub>. (New) The ink jet module of claim 29 wherein the thermoplastic bonding component includes a plurality of openings.--

50. (New) The method of claim 45 wherein the filter includes a repeating pattern of units having a plurality of openings.--

51. (New) The method of claim <sup>50</sup><sub>51</sub>, wherein a land between the units is at least 50 microns.

*DS Work*  
*Sub E*  
52  
--52. (New) An ink jet printing module comprising a piezoelectric element having a surface, and a thermoplastic bonding component heat-bonded to the surface, wherein the thermoplastic bonding component has a thickness between 1 micron and 150 microns.--

53  
--53. (New) The ink jet printing module of claim 52, wherein the thermoplastic bonding component has a thickness between 10 microns and 125 microns.--

54  
--54. (New) The ink jet printing module of claim 52, wherein the thermoplastic bonding component has a thickness between 20 and 50 microns.--

55  
--55. (New) The ink jet printing module of claim 52, wherein the thermoplastic bonding component includes a first surface heat-bonded to the surface of the piezoelectric element and a second surface heat-bonded to a surface of an ink jet printing module component.--

56  
--56. (New) The ink jet printing module of claim 52, wherein the thermoplastic bonding component includes an electrode pattern.--

57  
--57. (New) The ink jet printing module of claim 52, wherein the piezoelectric element is lead zirconium titanate.--

58  
--58. (New) The ink jet printing module of claim 52, wherein the thermoplastic bonding component includes a polyimide.--

59  
--59. (New) The ink jet printing module of claim 52, further comprising an ink channel, the piezoelectric element being positioned to subject ink within the channel to jetting pressure, and electrical contacts arranged for activation of the piezoelectric element.--

60  
--60. (New) The ink jet printing module of claim 59, further comprising a series of channels.--

*DB  
Cmp*

*61*  
~~*64*~~ --61. (New) The ink jet printing module of claim *60*, wherein each of said channels is covered by a single piezoelectric element.--

*62*  
~~*64*~~ --62. (New) The ink jet printing module of claim *59*, wherein the thermoplastic bonding component covers the ink channel and includes a filter.--

*Sub  
E1*  
*63*  
~~*64*~~ --63. (New) The ink jet printing module of claim *62*, wherein the filter including a repeating pattern of units having a plurality of openings and a land between the units is at least 50 microns.--

*64*  
~~*64*~~ --64. (New) The ink jet printing module of claim *63*, wherein the width is 300 to 495 microns.--

*68 65*  
~~*68*~~ --65. (New) The ink jet printing module of claim *52*, further comprising an orifice plate and a protector strip adhered to the orifice plate, wherein either the orifice plate or the protector strip includes a thermoplastic bonding material.--